

**S/N 10/723,474**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Suan J. Boon

Examiner: DiLinh Nguyen

Serial No.: 10/723,474

Group Art Unit: 2814

Filed: November 26, 2003

Docket No.: 303.601US2

Title: ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM  
WAFER LEVEL PACKAGING

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**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on December 13, 2007. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office Action, thereby moving the deadline for response from March 13, 2008 to April 13, 2008 (Sunday).